Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	100	V
RMS Reverse Voltage		$V_{R(RMS)}$	71	V
Forward Continuous Current (Note 5)		I_{FM}	250	mA
Repetitive Peak Forward Current		I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs	I_{FSM}	4	A
	@ t = 1.0ms		1.0	
	@ t = 1.0s		0.5	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	357	°C/W
Thermal Resistance Junction to Solder Point	$R_{\theta JSP}$	255	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	—	V	I_R = 2.5µA
Forward Voltage	V_F	—	0.715	V	I_F = 1.0mA
		—	0.855		I_F = 10mA
		—	1.0		I_F = 50mA
		—	1.25		I_F = 150mA
Reverse Current (Note 6)	I_R	—	0.5	µA	V_R = 80V
		—	50	µA	V_R = 80V, T_J = +150°C
		—	30	µA	V_R = 25V, T_J = +150°C
		—	30	nA	V_R = 25V
Total Capacitance	C_T	—	1.5	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{RR}	—	4.0	ns	I_F = I_R = 10mA, I_{RR} = 0.1 x I_R, R_L = 100Ω
Forward Recovery Voltage	V_{FR}	—	1.75	V	I_F = 10mA, t_R = 20ns

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, please see http://www.diodes.com/package-outlines.html for the latest version.
6. Short duration pulse test used to minimize self-heating effect.

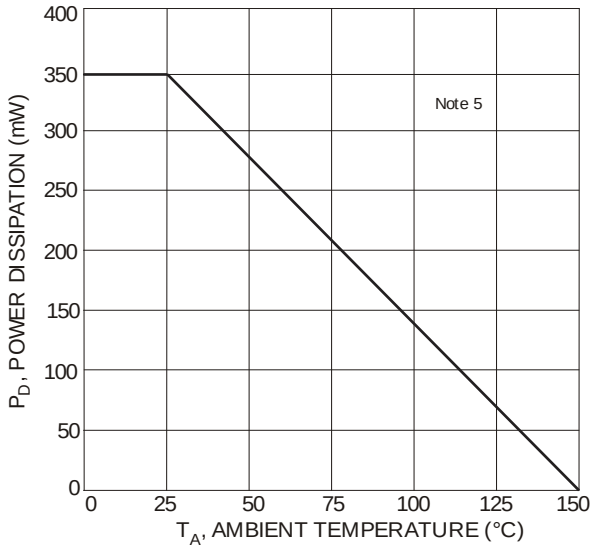

Fig. 1 Power Derating Curve, Total Package

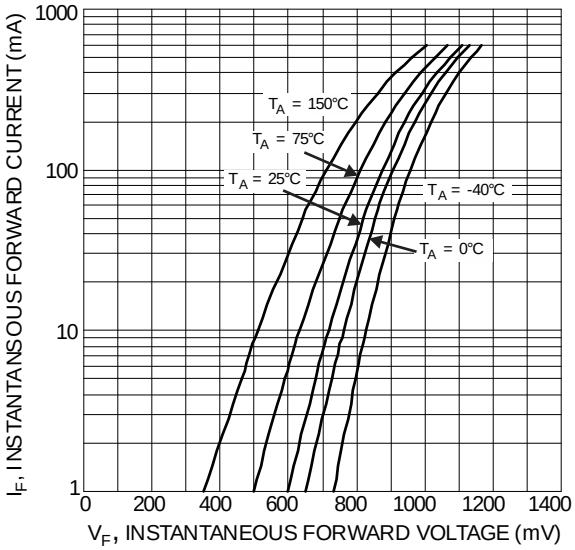

Fig. 2 Typical Forward Characteristics

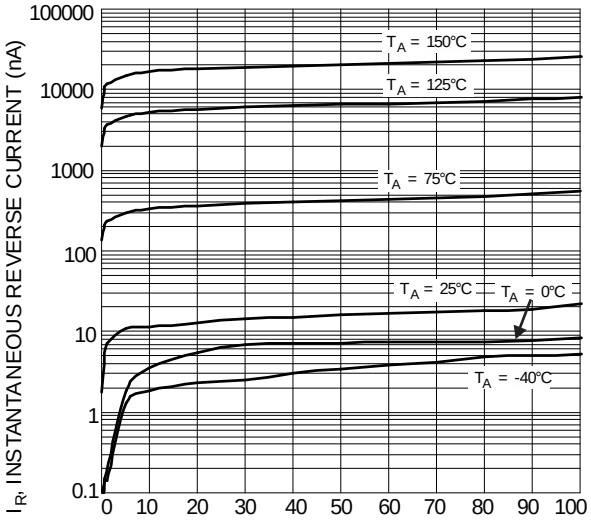

Fig. 3 Typical Reverse Characteristics, Per Element

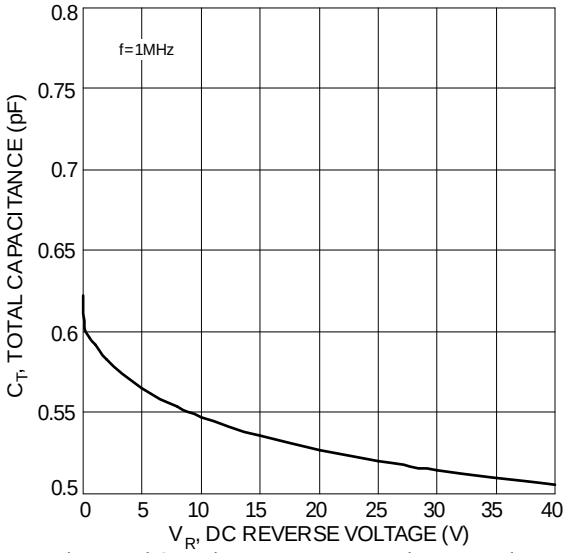

Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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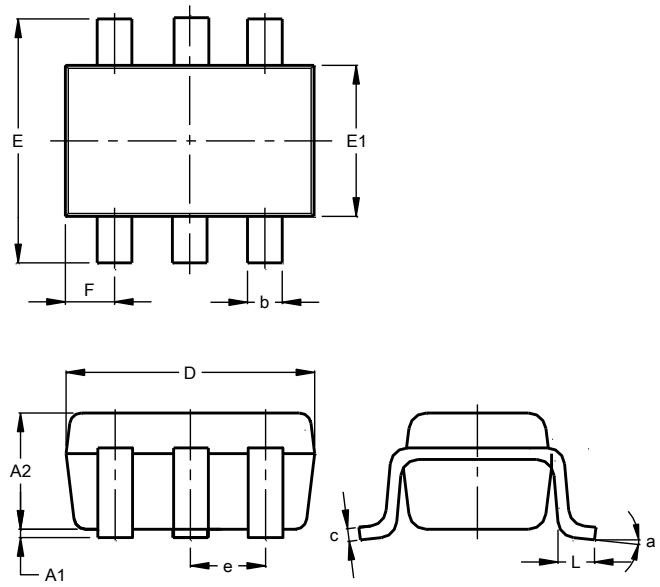

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Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	–
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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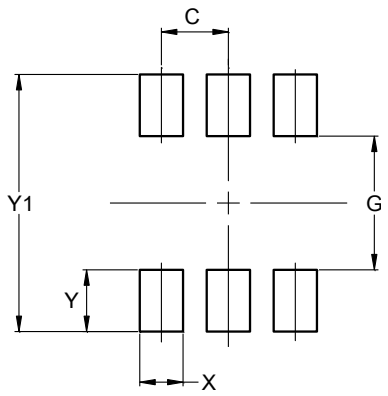

Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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